

May 2010

# FODM8071 3.3V/5V Logic Gate Output Optocoupler with High Noise Immunity

#### **Features**

- High noise immunity characterized by common mode rejection
  - 20kV/µs minimum common mode rejection
- High speed
  - 20Mbit/sec date rate (NRZ)
  - 55ns max. propagation delay
  - 20ns max. pulse width distortion
  - 30ns max. propagation delay skew
- 3.3V and 5V CMOS compatibility
- Specifications guaranteed over 3V to 5.5V supply voltage and -40°C to +110°C temperature range
- Safety and regulatory approvals
  - UL1577, 3750 VAC<sub>RMS</sub> for 1 min.
  - IEC60747-5-2 (pending)

## **Applications**

- Microprocessor system interface
  - SPI, I<sup>2</sup>C
- Industrial fieldbus communications
  - DeviceNet, CAN, RS485
- Programmable logic control
- Isolated data acquisition system
- Voltage level translator

## **Description**

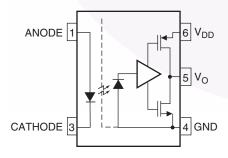
The FODM8071 is a 3.3V/5V high-speed logic gate output Optocoupler, which supports isolated communications allowing digital signals to communicate between systems without conducting ground loops or hazardous voltages. It utilizes Fairchild's patented coplanar packaging technology, Optoplanar<sup>®</sup>, and optimized IC design to achieve high noise immunity, characterized by high common mode rejection specifications.

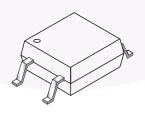
This high-speed logic gate output optocoupler, housed in a compact 5-Pin Mini-Flat package, consists of a high-speed AlGaAs LED at the input coupled to a CMOS detector IC at the output. The detector IC comprises an integrated photodiode, a high-speed transimpedance amplifier and a voltage comparator with an output driver. The CMOS technology coupled with a high efficiency LED achieves low power consumption as well as very high speed (55ns propagation delay, 20ns pulse width distortion).

#### **Related Resources**

- www.fairchildsemi.com/products/opto/
- www.fairchildsemi.com/pf/FO/FOD8001.html
- www.fairchildsemi.com/pf/FO/FOD0721.html

#### **Functional Schematic**





### **Truth Table**

| LED | Output |
|-----|--------|
| Off | High   |
| On  | Low    |

### **Pin Definitions**

| Number | Name            | Function Description  |
|--------|-----------------|-----------------------|
| 1      | ANODE           | Anode                 |
| 3      | CATHODE         | Cathode               |
| 4      | GND             | Output Ground         |
| 5      | V <sub>O</sub>  | Output Voltage        |
| 6      | V <sub>DD</sub> | Output Supply Voltage |

## Safety and Insulation Ratings for Mini-Flat Package (SO5 Pin)

As per IEC60747-5-2 (Pending Certification). This optocoupler is suitable for "safe electrical insulation" only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

| Symbol            | Parameter  | Min.            | Тур.      | Max. | Unit              |
|-------------------|--|-----------------|-----------|------|-------------------|
|                   | Installation Classifications per DIN VDE 0110/1.89 Table 1   |                 |           |      |                   |
|                   | For rated main voltage < 150Vrms   |                 | I-IV      |      |                   |
|                   | For rated main voltage < 300Vrms   | 1               | I-III     |      |                   |
|                   | Climatic Classification  |                 | 40/110/21 |      |                   |
|                   | Pollution Degree (DIN VDE 0110/1.89)   |                 | 2         |      |                   |
| CTI               | Comparative Tracking Index   | 175             |           |      |                   |
| V <sub>PR</sub>   | Input to Output Test Voltage, Method b, VIORM x 1.875 = $V_{PR}$ , 100% Production Test with $t_{m}$ = 1 sec, Partial Discharge < 5 pC | 1060            |           |      | V                 |
| V <sub>PR</sub>   | Input to Output Test Voltage, Method a, VIORM x 1.5 = $V_{PR}$ , Type and Sample Test with $t_{m}$ = 60 sec, Partial Discharge < 5 pC  | 848             |           |      | V                 |
| V <sub>IORM</sub> | Max Working Insulation Voltage   | 565             |           |      | V <sub>peak</sub> |
| V <sub>IOTM</sub> | Highest Allowable Over Voltage   | 4000            |           |      | V <sub>peak</sub> |
|                   | External Creepage  | 5.0             |           |      | mm                |
|                   | External Clearance   | 5.0             |           |      | mm                |
|                   | Insulation Thickness   | 0.5             |           |      | mm                |
| T <sub>Case</sub> | Safety Limit Values, Maximum Values allowed in the event of a failure, Case Temperature  | 150             |           |      | °C                |
| R <sub>IO</sub>   | Insulation Resistance at T <sub>STG</sub> ,V <sub>IO</sub> = 500V  | 10 <sup>9</sup> |           |      | Ω                 |

# Absolute Maximum Ratings (T<sub>A</sub> = 25°C unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol           | Parameter   | Value                        | Units |
|------------------|---|------------------------------|-------|
| T <sub>STG</sub> | Storage Temperature   | -40 to +125                  | °C    |
| T <sub>OPR</sub> | Operating Temperature   | -40 to +110                  | °C    |
| TJ               | Junction Temperature  | -40 to +125                  | °C    |
| T <sub>SOL</sub> | Lead Solder Temperature (Refer to Reflow Temperature Profile) | 260 for 10sec                | °C    |
| I <sub>F</sub>   | Forward Current   | 20                           | mA    |
| V <sub>R</sub>   | Reverse Voltage   | 5                            | V     |
| V <sub>DD</sub>  | Supply Voltage  | 0 to 6.0                     | V     |
| Vo               | Output Voltage  | -0.5 to V <sub>DD</sub> +0.5 | V     |
| Io               | Average Output Current  | 10                           | mA    |
| PDI              | Input Power Dissipation <sup>(1)(3)</sup>                     | 40                           | mW    |
| PDO              | Output Power Dissipation <sup>(2)(3)</sup>                    | 70                           | mW    |

## **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

| Symbol          | Parameter                      | Min. | Max. | Unit |
|-----------------|--------------------------------|------|------|------|
| T <sub>A</sub>  | Ambient Operating Temperature  | -40  | +110 | °C   |
| V <sub>DD</sub> | Supply Voltages <sup>(4)</sup> | 3.0  | 5.5  | V    |
| V <sub>FL</sub> | Logic Low Input Voltage        | 0    | 0.8  | V    |
| I <sub>FH</sub> | Logic High Input Current       | 5    | 16   | mA   |
| I <sub>OL</sub> | Logic Low Output Current       | 0    | 7    | mA   |

### **Isolation Characteristics**

(Apply over all recommended conditions, typical value is measured at  $T_A = 25$ °C)

| Symbol           | Parameter                      | Conditions   | Min.             | Тур. | Max. | Units              |
|------------------|--------------------------------|--|------------------|------|------|--------------------|
| V <sub>ISO</sub> | Input-Output Isolation Voltage | freq = 60Hz, t = 1.0min,<br>$I_{L-O} \le 10\mu A^{(5)(6)}$ | 3750             |      |      | Vac <sub>RMS</sub> |
|                  |                                | I <sub>I-O</sub> ≤ 10μΑ <sup>(σ)(σ)</sup>                  |                  |      |      |                    |
| R <sub>ISO</sub> | Isolation Resistance           | $V_{I-O} = 500V^{(5)}$                                     | 10 <sup>11</sup> |      |      | Ω                  |
| C <sub>ISO</sub> | Isolation Capacitance          | $V_{I-O} = 0V$ , freq = 1.0MHz <sup>(5)</sup>              |                  | 0.2  |      | pF                 |

#### Notes:

- 1. Derate linearly from 95°C at a rate of -1.4mW/°C
- 2. Derate linearly from 100°C at a rate of -3.47mW/°C.
- 3. Functional operation under these conditions is not implied. Permanent damage may occur if the device is subjected to conditions outside these ratings.
- 4. 0.1µF bypass capacitor must be connected between 4 and 6.
- 5. Device is considered a two terminal device: Pins 1, and 3 are shorted together and Pins 4, 5, and 6 are shorted together.
- 6. 3,750 VAC<sub>RMS</sub> for 1 minute duration is equivalent to 4,500 VAC<sub>RMS</sub> for 1 second duration.

## **Electrical Characteristics** (Apply over all recommended conditions)

(T<sub>A</sub> = -40°C to +110°C,  $3.0\text{V} \le \text{V}_{DD} \le 5.5\text{V}$ ), unless otherwise specified. Typical value is measured at T<sub>A</sub> = 25°C and V<sub>DD</sub> = 3.3V.

| Symbol           | Parameter                          | Test Conditions                                      | Min.                   | Тур.   | Max. | Units |
|------------------|------------------------------------|--|------------------------|--------|------|-------|
| INPUT CH         | IARACTERISTICS                     |  |                        |        |      |       |
| V <sub>F</sub>   | Forward Voltage                    | I <sub>F</sub> = 10mA, Fig. 1                        | 1.05                   | 1.35   | 1.8  | V     |
| BV <sub>R</sub>  | Input Reverse Breakdown<br>Voltage | I <sub>R</sub> = 10μA                                | 5                      | 15     |      | V     |
| I <sub>FHL</sub> | Threshold Input Current            | Fig. 2   |                        | 2.8    | 5    | mA    |
| OUTPUT           | CHARACTERISTICS                    |  |                        |        |      |       |
| I <sub>DDL</sub> | Logic Low Output Supply            | $V_{DD} = 3.3V$ , $I_F = 10mA$ , Fig. 3, 5           |                        | 3.3    | 4.8  | mA    |
|                  | Current                            | $V_{DD} = 5.0V, I_F = 10mA, Fig. 3, 6$               |                        | 4.0    | 5.0  | mA    |
| I <sub>DDH</sub> | Logic High Output Supply           | $V_{DD} = 3.3V, I_F = 0mA, Fig. 4$                   |                        | 3.3    | 4.8  | mA    |
|                  | Current                            | V <sub>DD</sub> = 5.0V, I <sub>F</sub> = 0mA, Fig. 4 |                        | 4.0    | 5.0  | mA    |
| V <sub>OH</sub>  | Logic High Output Voltage          | $V_{DD} = 3.3V, I_{O} = -20\mu A, I_{F} = 0mA$       | V <sub>DD</sub> – 0.1V | 3.3    |      | V     |
|                  |                                    | $V_{DD} = 3.3V, I_{O} = -4mA, I_{F} = 0mA$           | V <sub>DD</sub> – 0.5V | 3.1    |      | V     |
|                  |                                    | $V_{DD} = 5.0V, I_{O} = -20\mu A, I_{F} = 0mA$       | V <sub>DD</sub> – 0.1V | 5.0    |      | V     |
|                  |                                    | $V_{DD} = 5.0V, I_{O} = -4mA, I_{F} = 0mA$           | V <sub>DD</sub> – 0.5V | 4.9    |      | V     |
| V <sub>OL</sub>  | Logic Low Output Voltage           | $I_{O} = 20\mu A, I_{F} = 10mA$                      |                        | 0.0027 | 0.01 | V     |
|                  |                                    | I <sub>O</sub> = 4mA, I <sub>F</sub> = 10mA          |                        | 0.27   | 0.8  | V     |

## Switching Characteristics (Apply over all recommended conditions)

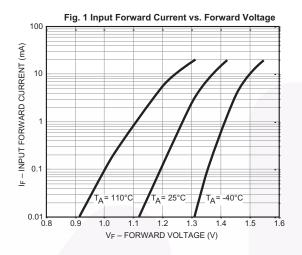
(T<sub>A</sub> = -40°C to +110°C, 3.0V  $\leq$  V<sub>DD</sub>  $\leq$  5.5V, I<sub>F</sub> = 5mA), unless otherwise specified. Typical value is measured at T<sub>A</sub> = 25°C and V<sub>DD</sub> = 3.3V

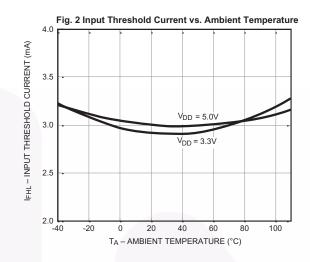
| Symbol                   | Parameter  | Test Conditions   | Min. | Тур. | Max. | Units |
|--------------------------|--|---|------|------|------|-------|
| Date Rate <sup>(7)</sup> |  |   |      |      | 20   | Mbps  |
| t <sub>PW</sub>          | Pulse Width  |   | 50   |      |      | ns    |
| t <sub>PHL</sub>         | Propagation Delay Time to Logic Low Output                         | C <sub>L</sub> = 15pF, Fig. 7, 8, 12  |      | 31   | 55   | ns    |
| t <sub>PLH</sub>         | Propagation Delay Time to Logic High Output                        | C <sub>L</sub> = 15pF, Fig. 7, 8, 12  |      | 25   | 55   | ns    |
| PWD                      | Pulse Width Distortion,<br>  t <sub>PHL</sub> - t <sub>PLH</sub>   | C <sub>L</sub> = 15pF, Fig. 9, 10   |      | 5.5  | 20   | ns    |
| t <sub>PSK</sub>         | Propagation Delay Skew   | $C_L = 15pF^{(8)}$  |      |      | 30   | ns    |
| t <sub>R</sub>           | Output Rise Time (10% to 90%)                                      | Fig. 11, 12   |      | 5.8  |      | ns    |
| t <sub>F</sub>           | Output Fall Time<br>(90% to 10%)                                   | Fig. 11, 12   |      | 5.3  |      | ns    |
| CM <sub>H</sub>          | Common Mode Transient<br>Immunity at Output High                   | $I_F = 0$ mA, $V_O > 0.8V_{DD}$ , $V_{CM} = 1000$ V, $T_A = 25$ °C, Fig. $13^{(9)}$     | 20   | 40   |      | kV/µs |
| CM <sub>L</sub>          | Common Mode Transient<br>Immunity at Output Low                    | $I_F$ = 5mA, $V_O$ < 0.8V,<br>$V_{CM}$ = 1000V, $T_A$ = 25°C,<br>Fig. 13 <sup>(9)</sup> | 20   | 40   |      | kV/µs |
| C <sub>PDO</sub>         | Output Dynamic Power<br>Dissipation<br>Capacitance <sup>(10)</sup> |   |      | 4    |      | pF    |

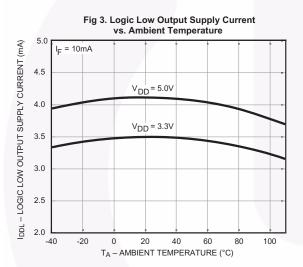
#### Notes:

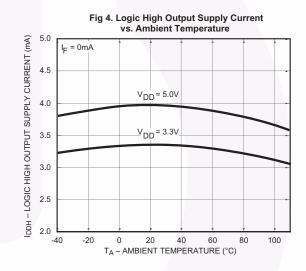
- 7. Data rate is based on 10MHz, 50% NRZ pattern with a 50nsec minimum bit time.
- 8.  $t_{PSK}$  is equal to the magnitude of the worst case difference in  $t_{PHL}$  and/or  $t_{PLH}$  that will be seen between any two units from the same manufacturing date code that are operated at same case temperature (±5°C), at same operating conditions, with equal loads ( $R_L = 350\Omega$  and  $C_L = 15pF$ ), and with an input rise time less than 5ns.
- 9. Common mode transient immunity at output high is the maximum tolerable positive dVcm/dt on the leading edge of the common mode impulse signal, Vcm, to assure that the output will remain high. Common mode transient immunity at output low is the maximum tolerable negative dVcm/dt on the trailing edge of the common pulse signal, Vcm, to assure that the output will remain low.
- 10.Unloaded dynamic power dissipation is calculated as follows: C<sub>PD</sub> x V<sub>DD</sub> x f + I<sub>DD</sub> + V<sub>PD</sub> where f is switched time in MHz.

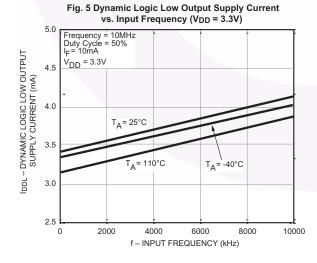
## Typical Performance Curves (Continued)

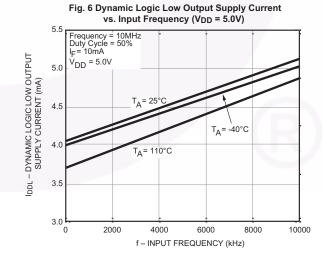




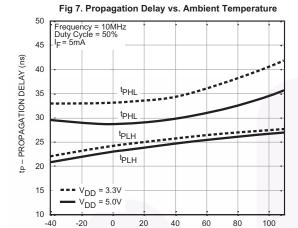


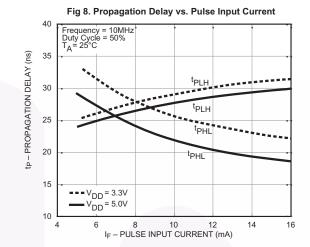


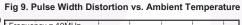




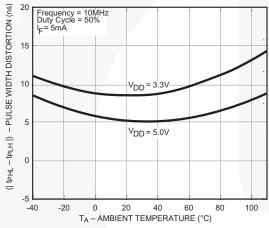
## Typical Performance Curves (Continued)

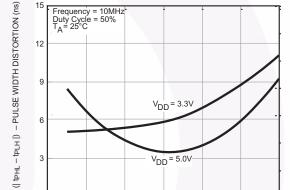






TA - AMBIENT TEMPERATURE (°C)





6

8

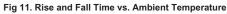
 $V_{DD} = 5.0V$ 

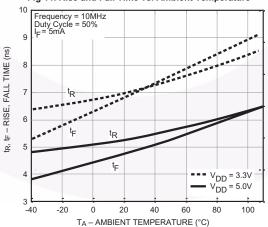
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I<sub>F</sub> – PULSE INPUT CURRENT (mA)

12

Fig 10. Pulse Width Distortion vs Pulse Input Current





16

## **Schematics**

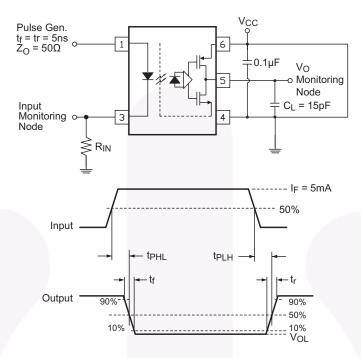


Figure 12. Test Circuit for Propagation Delay Time, Rise Time and Fall Time

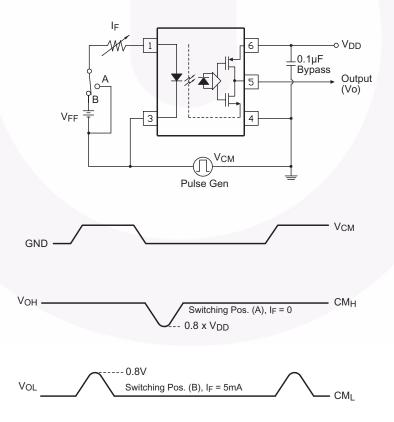
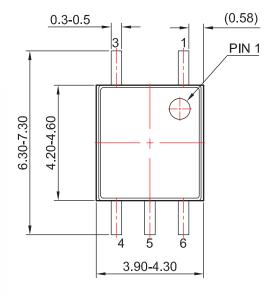
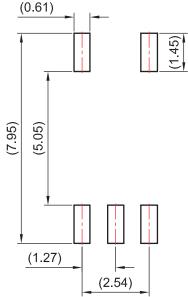
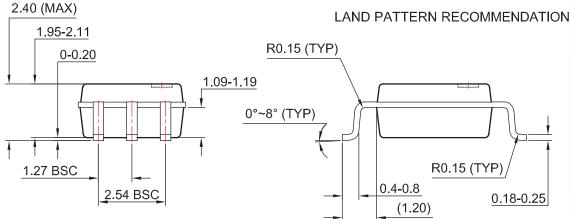


Figure 13. Test Circuit for Instantaneous Common Mode Rejection Voltage

# **Package Dimensions**







## Notes:

- 1. No standard applies to this package.
- 2. All dimensions are in millimeters.
- 3. Dimensions are exclusive of burrs, mold flash, and tie bar extrusion.
- 4. Drawings filesname and revision: MKT-MFP05A.

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

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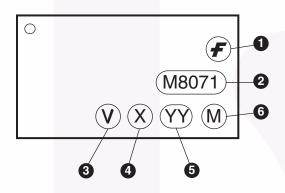
# **Ordering Information**

| Option    | ption Order Entry Identifier Description |  |
|-----------|--|--|
| No Suffix | FODM8071                                 | Mini-Flat 5-pin, shipped in tubes (100 units per tube) |
| R2        | FODM8071R2                               | Mini-Flat 5-pin, tape and reel (2,500 units per reel)  |



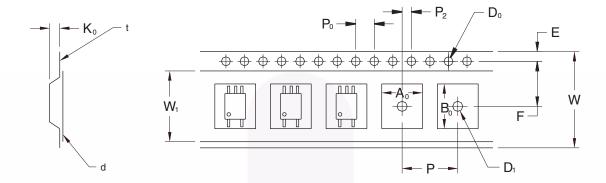
All packages are lead free per JEDEC: J-STD-020B standard.

# **Marking Information**



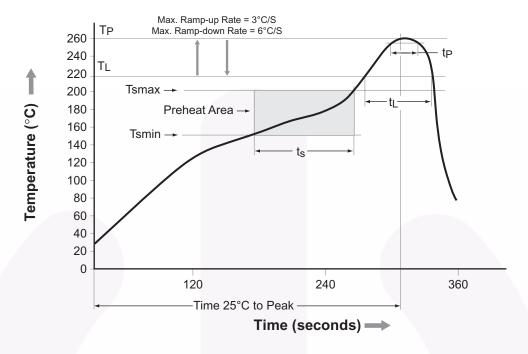
| Definiti | ons   |  |
|----------|---|--|
| 1        | Fairchild logo                                |  |
| 2        | Device number                                 |  |
| 3        | IEC60747-5-2 (VDE marking)                    |  |
| 4        | One digit year code, e.g., '9'                |  |
| 5        | Two digit work week ranging from '01' to '53' |  |
| 6        | Assembly package code                         |  |

# **Tape and Reel Dimensions**



|                                 |                | 2.54 Pitch        |
|---------------------------------|----------------|-------------------|
| Description                     | Symbol         | Dimensions (mm)   |
| Tape Width                      | W              | 12.00 +0.30/-0.10 |
| Tape Thickness                  | t              | 0.30 ±0.05        |
| Sprocket Hole Pitch             | P <sub>0</sub> | 4.00 ±0.10        |
| Sprocket Hole Diameter          | D <sub>0</sub> | 1.50 +0.10/-0.0   |
| Sprocket Hole Location          | E              | 1.75 ±0.10        |
| Pocket Location                 | F              | 5.50 ±0.10        |
|                                 | P <sub>2</sub> | 2.00 ±0.10        |
| Pocket Pitch                    | Р              | 8.00 ±0.10        |
| Pocket Dimension                | A <sub>0</sub> | 4.40 ±0.10        |
|                                 | B <sub>0</sub> | 7.30 ±0.10        |
|                                 | K <sub>0</sub> | 2.30 ±0.10        |
| Pocket Hole Diameter            | D <sub>1</sub> | 1.50 Min.         |
| Cover Tape Width                | W <sub>1</sub> | 9.20              |
| Cover Tape Thickness            | d              | 0.065 ±0.010      |
| Max. Component Rotation or Tilt |                | 10° Max.          |
| Devices Per Reel                |                | 2500              |
| Reel Diameter                   |                | 330mm (13")       |

## **Reflow Profile**



| Profile Feature   | Pb-Free Assembly Profile |
|---|--------------------------|
| Temperature Min. (Tsmin)                                  | 150°C                    |
| Temperature Max. (Tsmax)                                  | 200°C                    |
| Time (t <sub>S</sub> ) from (Tsmin to Tsmax)              | 60-120 seconds           |
| Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )          | 3°C/second max.          |
| Liquidous Temperature (T <sub>L</sub> )                   | 217°C                    |
| Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> ) | 60-150 seconds           |
| Peak Body Package Temperature                             | 260°C +0°C / -5°C        |
| Time (t <sub>P</sub> ) within 5°C of 260°C                | 30 seconds               |
| Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )        | 6°C/second max.          |
| Time 25°C to Peak Temperature                             | 8 minutes max.           |





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#### As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness

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#### PRODUCT STATUS DEFINITIONS

#### **Definition of Terms**

| Definition of Terms         |                       |   |
|-----------------------------|-----------------------|---|
| Datasheet<br>Identification | Product Status        | Definition  |
| Advance Information         | Formative / In Design | Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.   |
| Preliminary                 | First Production      | Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. |
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| Obsolete                    | Not In Production     | Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.  |

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